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Product Change Notification

Product Group: TC/Sunday August 30, 2026/PCN-TC-014-2026-REV-0



Secure Lead frame supply chain for T51 Automotive products

For further information, please contact your regional Vishay office.

CONTACT INFORMATION

Americas

David Bellomy
-
-
- United States -
Phone: (254)479-0010
Fax:
David.Bellomy@vishay.com

Europe

Michel Bouvier
-
-
- France -
Phone: +33 1 30 09 4123
Fax:
michel.bouvier@Vishay.com

Asia

Falco Hung
-
-
- Hong Kong -
Phone: +852 934 59069
Fax:
falco.hung@Vishay.com

Description of Change: Apply terminal 100% Sn plating before product assembly step instead of plating after the molding. No change in material content / product structure / FFF.

Reason for Change: Secure Lead frame supply chain for T51 Automotive products: introduce pre-plated Lead frames in order to simplify manufacturing process. Eliminate post mold plating by subcontractor and related logistics.

Expected Influence on Quality/Reliability/Performance: No.

Part Numbers/Series/Families Affected: T51*

Vishay Brand(S): Vishay Polytech

Time Schedule:

Start Shipment Date: Monday November 30, 2026

Sample Availability: Upon request.

Product Identification: N/A.

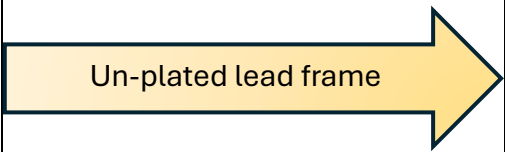
Qualification Data: Upon request.

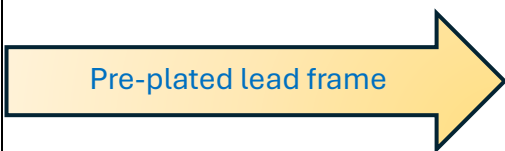
This PCN is considered approved, without further notification, unless we receive specific customer concerns before Wednesday September 30, 2026 or as specified by contract.

Issued By: Yuri Stangrit, yuri.stangrit@vishay.com

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Excerpt from T51 Polymer molded chip capacitors Process Flow Chart

	Step	Current process	Reference document
 Un-plated lead frame	18	Lead frame assembly	DTS-150
	19	Conductive paste cure	DTS-150
	20	Element coating	DTS-160
	21	Mold encapsulation	DTS-162
	22	Deflasher	DTS-164
 Terminal plating by subcon	23	Incoming inspection of Terminal plating (Outsource)	DTS-170
	24	Humidity conditioning after molding	DTS-171
	25	Marking	DTS-171

	Step	New process	Reference document
 Pre-plated lead frame	18	Lead frame assembly	DTS-150
	19	Conductive paste cure	DTS-150
	20	Element coating	DTS-160
	21	Mold encapsulation	DTS-162
	22	Deflasher	DTS-164
	23	Incoming inspection of Terminal plating (Outsource)	DTS-170
	24	Humidity conditioning after molding	DTS-171
	25	Marking	DTS-171